

Product Change Notification / JAON-16TWMA390

Date:

30-Mar-2021

Product Category:

Car Access, Wireless Modules

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3739.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products available in 32L VQFN (5x5x1.00 mm) package at ASCL assembly site.

Affected CPNs:

JAON-16TWMA390_Affected_CPN_03302021.pdf JAON-16TWMA390_Affected_CPN_03302021.csv

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products available in 32L VQFN (5x5x1.00 mm) package at ASCL assembly site.

Pre Change:

Using palladium coated gold (AuPd1) or palladium coated copper (PdCu) bond wire material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire material

Pre and Post Change Summary:

	Pre Cl	nange	Post Change			
Assembly Site	ASE Group	o Chung-Li	ASE Group Chung-Li			
	(ASCL)		(ASCL)			
Wire material	AuPd1	PdCu	CuPdAu			
Die attach material	EN-4900G		EN-4900G			
Molding compound material	G700LA		G700LA			
Lead frame material	C70)25	C7025			

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire material at ASCL assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: April 30, 2021 (date code: 2118)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2021					April 2021			
Workweek	10	11	12	13	14	15	16	17	18
Qual Report Availability					х				
Final PCN Issue Date					Х				
Estimated First Ship Date									х

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:October 06, 2020: Issued initial notification.**October 12, 2020:** Re-issued initial notification to remove comment on the qualification plan.**March 30, 2021:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on April 30, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_JAON-16TWMA390_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. JAON-16TWMA390 - CCB 3739.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products available in 32L VQFN (5x5x1.00 mm) package at ASCL assembly site.

Affected Catalog Part Numbers (CPN)

ATA5830-WNQW ATA5780N-WNQW ATA5830N-WNQW2 ATA5830N-WNQW ATA5830N-WNQW1 ATA5831-WNQW ATA8510-GHQW ATA8520-GHQW ATA8520D-GHQW ATA8520E-GHQW ATA8520-GHPW ATA8520D-GHPW ATA8520E-GHPW ATA5782-WNQW ATA8210-GHQW ATA5833-WNQW ATA5781-WNQW ATA5785-GHQW ATA8515-GHQW ATA8215-GHQW ATA5781N-WNQW ATA5833-WNQW-VAO ATA5781-WNQW-VAO ATA5785-GHQW-VAO